Customer Information Notification

202205018I : Minor Change in Carrier Tape Pocket Size for Packages 2.0x2.0/2.0x2.4

Note: This notice is NXP Company Proprietary.

Issue Date: May 18, 2022
Effective date:May 19, 2022

Management summary

Minor change in carrier tape pocket size for packages 2.0x2.0/2.0x2.4

Change Category

[ ]Wafer Fab Process
[ ]Wafer Fab Materials
[ ]Wafer Fab Location
[ ]Firmware
[ ]Assembly Process
[ ]Assembly Materials
[ ]Assembly Location
[ ]Other
[ ]Product Marking
[X]Mechanical Specification
[ ]Packing/Shipping/Labeling
[ ]Test Process
[ ]Test Equipment
[ ]Test Location
[ ]Design
[ ]Errata
[ ]Electrical spec./Test coverage

PCN Overview

Description

Minor change in carrier tape pocket size for packages 2.0x2.0 and 2.0x2.4:
2.0x2.0: from 2.3mm (A0) x 2.3mm (B0) to 2.2mm (A0) x 2.2mm (B0)
2.0x2.4: from 2.2mm (A0) x 2.7mm (B0) to 2.2mm (A0) x 2.6mm (B0)

Reason

To be compliant with requirements

Identification of Affected Products

Product identification does not change

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards. Customer Focus, Passion to Win.

NXP Quality Management Team.